TVNX210 VNX+ Carrier with 2 QMC sites, PCIe Gen3 x4, Rear-I/O

TVNX210-10R

Application Information

The TVNX210 is a VITA 90 compatible 19 mm VNX+ Plug-In Module (PIM) designed to provide system integrators with the flexibility and modularity they need when building high-performance I/O subsystems for a defense or aerospace platform.

The VNX+ QMC carrier provides two independent single-width QMC sites that can be populated with up to two single-width QMC modules or a double-width QMC module. The QMC sites are connected via a non-blocking PCIe Gen 3 switch that distributes the VNX+ backplane's x8 PCIe links from the expansion plane or the two x4 PCIe links from the data planes.

The full QMC I/O of the two QMC sites is accessible on the VNX+ backplane via the 400-pin High Speed Data Connector (HSDC), conforming to the VNX.PL-1-02.400-7.2.1.3 <Dual QMC Carrier> slot profile.

A Management Controller implemented according to VITA 46.11 allows QMC health status monitoring and communication with the VNX+ System Management.

Technical Information

- Form Factor: 19 mm VNX+ Payload PIM
- VNX.PL-1-02.400-7.2.1.3-<Dual QMC Carrier> VITA 90.1 slot profile
  - 400 pin HSDC
  - VS1 (12V) powered
  - PCIe Gen 3 x8 compliant interface in the Expansion Plane,
  - PCIe Gen 3 x4 compliant interfaces in the Data Planes
- Two single QMC sites
  - PCIe Gen3 x4
  - Full QMC I/O to VNX+ backplane
- Management controller (VITA 46.11)
  - QMC health status monitoring
  - VNX+ system management bus
- Operating temperature -40 °C to +85 °C

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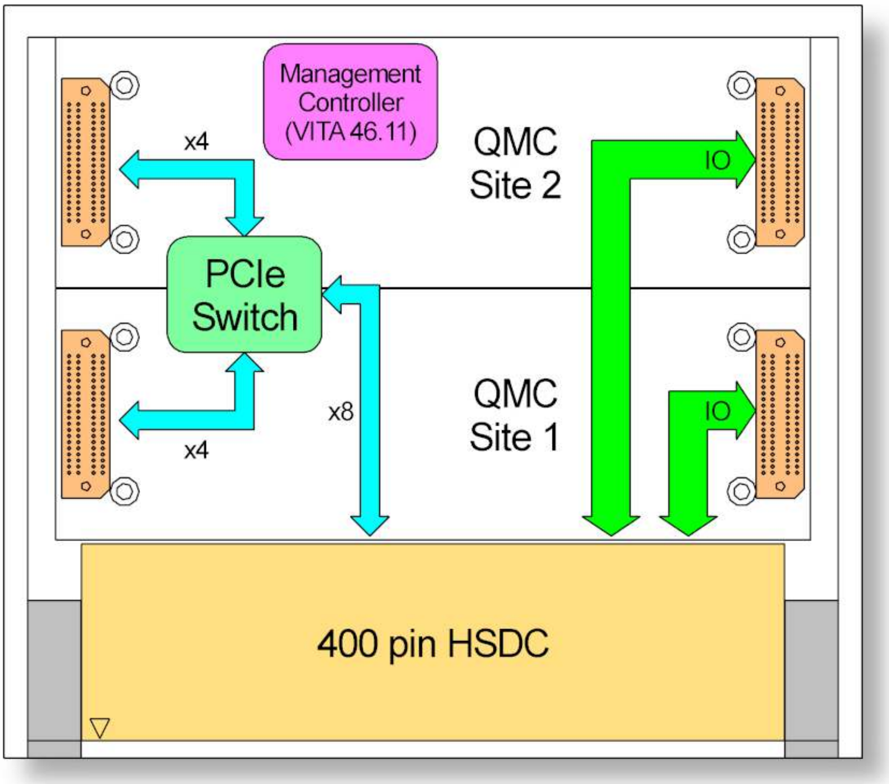

TVNX210 Blockdiagram

Order Information

RoHS Compliant

TVNX210-10R	VNX+ Carrier with 2 QMC Sites, PCIe Gen 3 x4, Rear I/O

For the availability of non-RoHS compliant (leaded solder) products please contact TEWS.

For the availability of conformal coated products, please contact TEWS.

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